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ning of each regular issue of the PCT Gazette.

(54) Title: INORGANIC POWDER, RESIN COMPOSITION FILLED WITH THE POWDER AND USE THEREOF

(57) Abstract: The present invention relates to an inorganic powder having a frequency-size distribution with multiple peaks, wherein the peaks are present at least in the particle size regions from 0.2 to 2  $\mu\text{m}$  and from 2 to 63  $\mu\text{m}$ , preferably with the maximum particle size being 63  $\mu\text{m}$  or less, the average particle size being from 4 to 30  $\mu\text{m}$ , and the mode size being from 2 to 35  $\mu\text{m}$ . The inorganic powder of the present invention is useful as a filler for a high thermally conductive member in electronic component-mounted circuit board required to have electrical insulating property and heat radiating performance, in that a heat radiating member comprising the powder can have thermal conductivity, the powder can provide a resin composition having excellent with-stand voltage characteristics for forming an insulative composition into a thin film and can be filled in the resin composition at a high density so as to improve heat radiating performance of the resin composition.

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